



SDI Review Form 1.6

Journal Name:	Journal of Engineering Research and Reports
Manuscript Number:	Ms_JERR_60632
Title of the Manuscript:	Addressing Package Voids on Extremely Small Leadframe Device
Type of the Article	Original Research Article

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/journal/10/editorial-policy>)

PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Compulsory REVISION comments		
Minor REVISION comments	<p>Dear Authors;</p> <p>After reviewing your paper, I have some comments to be answered.</p> <ol style="list-style-type: none"> 1. Keywords should be alphabetic order 2. Uptade and increase recent references 3. Resolution of figure 6 and figure 7 should be improved 4. All references should be cited in the text. 	
Optional/General comments		

PART 2:

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	(If yes, Kindly please write down the ethical issues here in details)	

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